

REMARKS

Reconsideration of the above-referenced application in view of the amendments and the following remarks is respectfully requested.

Claims 14-20 are pending in this case. Claims 14 and 15 have been amended to better define the scope of the claimed invention.

Claims 14-15, 17-20 stand rejected under 35 U.S.C. 103(a) as being unpatentable over Arima (U.S. Patent No. 5,281,151) in view of Khandros (U.S. Patent No. 5,346,861) and Dalal (U.S. Patent Application Publication 2001/0013423) and further in view of DiStefano, et al. (U.S. Patent No. 5,367,764) and further in view of Dalal, et al. (U.S. Patent No. 5,634,268). Claims 14 and 15 have been amended to adopt the Examiner's suggestion as to allowable subject matter. Therefore, Applicant respectfully requests that Claims 14 and 15, as well as Claims 17-20 depending therefrom, be allowed.

Claim 16 stands rejected under 35 U.S.C. 103(a) as being unpatentable over Arima (U.S. Patent No. 5,281,151) in view of Khandros (U.S. Patent No. 5,346,861) and Dalal (U.S. Patent Application Publication 2001/0013423) and further in view of DiStefano, et al. (U.S. Patent No. 5,367,764) and further in view of Amador, et al. (U.S. Patent No. 6,432,744). Applicant respectfully traverses the rejection. Amador is not available prior art since it and the claimed invention were, at the time the invention was made, owned by the same person (Texas Instruments Incorporated) or subject to an obligation of assignment to the same person (35 U.S.C. 103(c)). Note also that Amador and the instant application claimed priority from provisional applications which were both filed on 11/20/1997. With regard to the other references relied upon in this rejection, Claim 16 includes a description of the relative spacings of the chip bond pads and the conductive fibers in the adhesive layer. As shown in Figure 12 of the instant specification, the conductive fibers exist throughout the breadth of the

adhesive layer (or at least throughout the region of the adhesive layer where contacts are expected to be made), including at points between the locations of the bond pads. In contrast, Arima's through-holes or vias exist in a one-to-one relation to the bond pads. The remaining cited available references do not cure this deficiency of Arima. Therefore, Applicant respectfully submits that Claim 16 is patentable over the cited references.

Applicant respectfully requests reconsideration and withdrawal of the rejections and allowance of Claims 14-20. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

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Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Michael K. Skrehot', written in a cursive style.

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